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(54) Title: FAN OUT PACKAGE FOR A SEMICONDUCTOR POWER MODULE

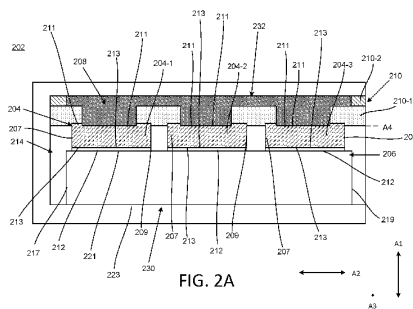


FIG. 2A

(57) Abstract: A fan out package (102) (202) (302-1) (302-2) (402-1) (402-2) (502-1) (502-2) (602) (702) (802-1) (802-2) (902-1) (902-2) (1002-1) (1002-2) may include a plurality of semiconductor dies (104) (204) (304) (404) (504) (604) (704) (804) (904) (1004), each of the semiconductor dies including a first surface and a second surface opposite to the first surface. The fan out package includes a redistribution layer (108) (208) (308) (408) (508) (608) (708) (808) (908) (1008) coupled to the first surface of each of the plurality of semiconductor dies, a dieback conductive member (106) (206) (306) (406) (506) (606) (706) (806) (906) (1006) coupled to the second surface of each of the plurality of semiconductor dies, and an encapsulation material (114) (214) (314) (414) (514) (614) (814) (914) (1014) coupled to the plurality of semiconductor dies and the dieback conductive member.

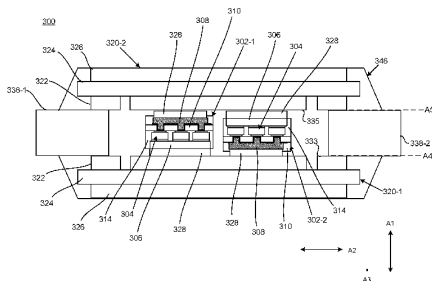


FIG. 3

[Continued on next page]

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